



Access



Evolution



Productivity

## IBS-E

### ICC Backside Spot Pressure Test Tool

#### Applications

The ICC Backside Spot Pressure test tool (left side on the picture) is designed to test the IC Module adhesion resistance into the card body. It complies to the latest MasterCard CQM requirements (TM-423 test method). This test is a destructive test with concentrated pressure on the reverse center side of the contact location.

- IC module adhesion qualification.
- Quality control / Production control.
- Support to CQM certification and audit.

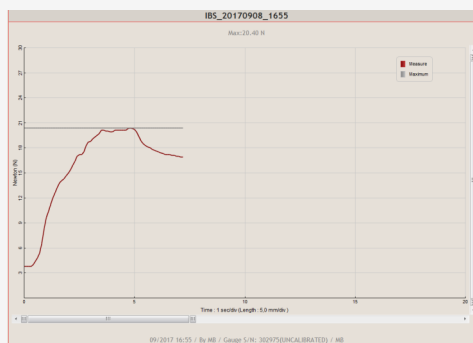
#### Key benefits

This version comes with digital gauge connected to a PC and a dedicated utility.

- Easy-to prepare the opening into the card body with a dedicated accessory tool to drill an opening.



Preparation tool



#### Technical characteristics

##### Max gauge force

500 N (Newtons)

##### Accessories

Preparation tool included

##### Dimensions

W x D x H: 190 x 235 x 380 mm

##### Weight

11,6 Kg

*In compliance with E.C. directives*

#### Associated products

Other MULANN products are nicely complementary:

- BWT-A or WTT-A control tools for bending stiffness and wrapping test
- TFD-A or TFD-P30 testers for dynamic bending